PK454 (v1.0) January 28, 2011

100% Material Declaration Data Sheet FGG1156

Average Weight: 5.4930 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.256153**	**4.663%**
	Silicon	7440-21-3	100.00		0.256153	
Die Attach Material					**0.072582**	**1.321%**
	Silver	7440-22-4	77.50		0.056251	
	Bismaleimide monomer	Trade Secret	15.00		0.010887	
	Acrylate monomer	Trade Secret	7.50		0.005444	
Mold Compound					**2.292107**	**41.728%**
	Epoxy Resin A	Trade Secret	3.00		0.068763	
	Epoxy Resin B	Trade Secret	3.00		0.068763	
	Phenol Resin A	Trade Secret	3.00		0.068763	
	Phenol Resin B	Trade Secret	3.00		0.068763	
	Metal Hydroxide	Trade Secret	1.50		0.034382	
	Carbon Black	1333-86-4	0.30		0.006876	
	Silica Fused	60676-86-0	70.90		1.625104	
	Silica Fused	7631-86-9	15.00		0.343816	
	Silica, crystalline	14808-60-7	0.30		0.006876	
Gold Wire					**0.029878**	**0.544%**
	Gold	7440-57-5	99.05		0.029594	
	Palladium	7440-05-3	0.95		0.000284	
	Calcium	7440-70-2	0.00		0.000001	
Solder Balls					**0.968296**	**17.628%**
	Tin	7440-31-5	96.50		0.924723	
	Silver	7440-22-4	3.00		0.038732	
	Copper	7440-50-8	0.50		0.004841	

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Substrate					**1.874003**	**34.116%**
	Copper (Cu)	7440-50-8	37.36		0.700097	
	Nickel (Ni)	7440-02-0	3.96		0.074124	
	Gold (Au)	7440-57-5	0.47		0.008863	
	Epoxy resin	NA	22.11		0.414407	
	Inorganic filler	21645-51-2	7.86		0.147217	
	Continuous filament fiber glass	65997-17-3	19.90		0.372951	
	Copper (Cu)	7440-50-8	2.62		0.049072	
	Talc	14807-96-6	0.29		0.005364	
	Morpholine derivative	NA	0.17		0.003218	
	Barium Sulfate	7727-43-7	2.52		0.047199	
	Silica	7631-86-9	0.06		0.001073	
	Dipropylene Glycol Monomethyl Ether	34590-94-8	1.49		0.027891	
	Epoxy resin	85954-11-6	1.20		0.022527	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
01/28/11	1.0	Initial Xilinx release.

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